Timing Generator for Progressive Scan CCD Image Sensor

Description

The CXD2460R is an IC developed to generate the timing pulses required by Progressive Scan CCD image sensors as well as signal processing circuits.

Features

- Electronic shutter function
- Supports non-interlaced operation
- Base oscillation frequency 28.636MHz
- Horizontal drive frequency switchable between 14.3/7.2MHz
- Switchable between FINE (Progressive Scan) mode or DRAFT (high-speed draft) mode
- Built-in vertical driver

Applications

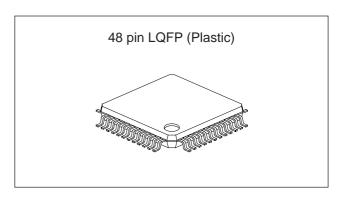
Progressive Scan CCD cameras

Structure

Silicon gate CMOS IC

Applicable CCD Image Sensor

ICX205AK



Absolute Maximum Ratings

• Supply voltage VDDa, VDDb, VDDc, VDDd

	Vss - 0.5 to $Vss + 7.0$	V
 Supply voltage Vss 	VL - 0.5 to $VL + 26.0$	٧
 Supply voltage VH 	VL - 0.5 to $VL + 26.0$	٧
 Supply voltage VM 	VL - 0.5 to $VL + 26.0$	٧
• Input voltage Vi Vs	s - 0.5 to VDDa,b,c,d + 0.5	٧
• Output voltage Vo Vs	s - 0.5 to VDDa,b,c,d + 0.5	٧
Operating temperature	e	

	Topr	-20 to +75	°C.
Storage temp	erature		

Tstg -55 to +150 °C

-20 to +75

Recommended Operating Conditions

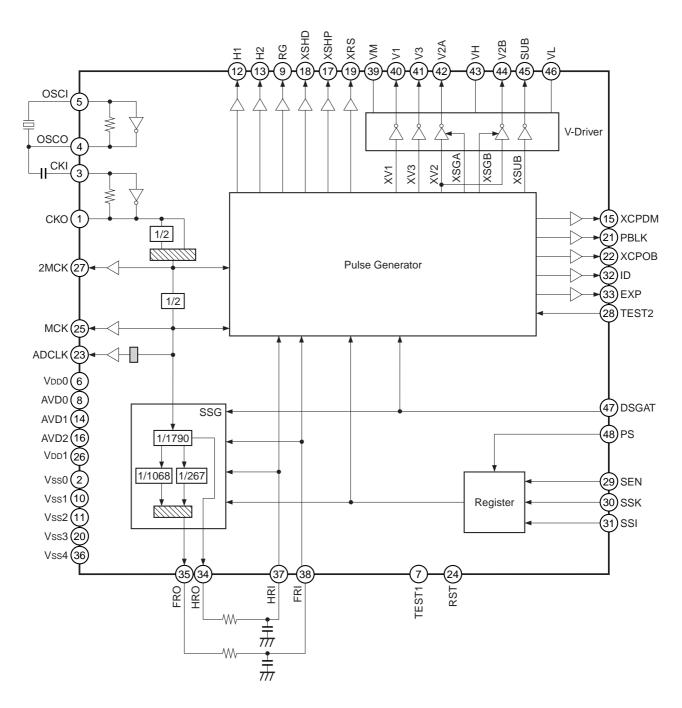
 Supply voltage 1 	Vdda,	Vddb, Vddd	
		3.0 to 3.6	V
• Supply voltage 2	VDDC	3.0 to 5.25	V
• Supply voltage 3	VH	14.25 to 15.75	V
• Supply voltage 4	VL	−9.0 to −5.0	V
• Supply voltage 5	VM	0	V
Operating temperations	ature		

Topr

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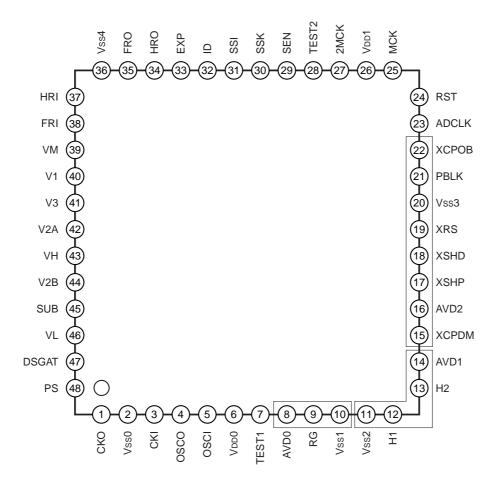
°C

Block Diagram



XSGA and XSGB are readout pulses that use V2A and V2B, respectively, as the VH value.

Pin Configuration (Top View)



The enclosed pins use separate power supplies.

Pin Description

Pin No.	Symbol	I/O	Description
1	СКО	0	Oscillator output. (28.6MHz)
2	Vss0	_	GND
3	CKI	I	Oscillator input. (28.6MHz)
4	osco	0	Inverter output for oscillation. (28.6MHz)
5	OSCI	I	Inverter input for oscillation. (28.6MHz)
6	VDD0	_	Power supply.
7	TEST1	I	Test. With pull-down resistor. Fix to low.
8	AVD0	_	Power supply.
9	RG	0	Reset gate pulse output.
10	Vss1	_	GND
11	Vss2	_	GND
12	H1	0	Clock output for horizontal CCD drive.
13	H2	0	Clock output for horizontal CCD drive.
14	AVD1	_	Power supply.
15	XCPDM	0	Clamp pulse.
16	AVD2	_	Power supply.
17	XSHP	0	Sample-and-hold pulse.
18	XSHD	0	Sample-and-hold pulse.
19	XRS	0	Sample-and-hold pulse.
20	Vss3	_	GND
21	PBLK	0	Blanking cleaning pulse.
22	ХСРОВ	0	Clamp pulse.
23	ADCLK	0	Clock output for AD conversion.
24	RST	I	Reset (Low: Reset, High: Normal operation). Always input one reset pulse during power-on.
25	MCK	0	Clock output for digital circuit.
26	VDD1	_	Power supply.
27	2MCK	0	Clock output for digital circuit.
28	TEST2	I	Test. Fix to high.
29	SEN	I	PS = High: Drive frequency setting input. PS = Low: Serial setting strobe input.
30	SSK	I	PS = High: Readout method setting input. PS = Low: Serial setting clock input.
31	SSI	I	PS = High: Shutter speed setting input. PS = Low: Serial setting data input.
32	ID	0	Line identification signal output write enable pulse output or XSUB output.
33	EXP	0	Pulse output indicating exposure is underway or checksum result output.
	•		•

Pin No.	Symbol	I/O	Description
34	HRO	0	Horizontal sync signal (HR) output or XSGA output.
35	FRO	0	Vertical sync signal (FR) output or XSGB output.
36	Vss4	_	GND
37	HRI	I	Horizontal sync signal (HR) input.
38	FRI	I	Vertical sync signal (FR) input.
39	VM	_	GND (vertical clock driver GND).
40	V1	0	Clock output for vertical CCD drive.
41	V3	0	Clock output for vertical CCD drive.
42	V2A	0	Clock output for vertical CCD drive.
43	VH	_	15V power supply (vertical clock driver power supply).
44	V2B	0	Clock output for vertical CCD drive.
45	SUB	0	CCD electric charge sweep pulse output.
46	VL	_	-8.0V power supply (vertical clock driver power supply).
47	DSGAT	I	Output stop (Same operation control as SLP when low).
48	PS	I	Parallel/serial switching for mode setting input method. (High: Parallel, Low: Serial) With pull-down resistor.

Electrical Characteristics

DC Characteristics

(Within the recommended operating conditions)

Item	Pins	Symbol	Conditions	Min.	Тур.	Max.	Unit
Supply voltage 1			Conditions	3.0		3.6	V
	VDDO, VDD1,	Vool			3.3		
Supply voltage 2	AVD0	VDDb		3.0	3.3	3.6	V
Supply voltage 3		VDDC		3.0	5.0	5.25	V
Supply voltage 4	AVD2	VDDd		3.0	3.3	3.6	V
Supply voltage 5	VH	VH		14.5	15.0	15.5	V
Supply voltage 6	VM	VM		_	0.0	_	V
Supply voltage 7	VL	VL		-9.0		-5.0	V
Input voltage 1	CKI	V _{IH1}		0.7Vppa			V
input voltage 1	OKI	VIL1				0.3VDDa	V
Input voltage 2	TECT4 DC	V _{IH2}		0.7Vpda			V
iliput voltage 2	TEST1, PS	VIL2				0.3VDDa	V
lancit valtage 2	RST, TEST2,	Vt + 1		0.8VDDa			٧
Input voltage 3	SEN, SSK, SSI, HRI, FRI, DSGAT	Vt – 1				0.2VDDa	٧
Outrot volta na 4	CKO, MCK,	Vон1	Feed current where IoH = −10.0mA	VDDa - 0.8			٧
Output voltage 1	2MCK	Vol1	Pull-in current where IoL = 7.2mA			0.4	٧
Output voltage 2	D.C.	Voн2	Feed current where IoH = −3.3mA	VDDb - 0.8			V
Output voltage 2	RG	Vol2	Pull-in current where IoL = 2.4mA			0.4	٧
Output voltage 2	U4 U2	Vонз	Feed current where IoH = −36.0mA	VDDC - 0.8			V
Output voltage 3	H1, H2	Vol3	Pull-in current where IoL = 24.0mA			0.4	V
Output voltage 4	XCPDM, XSHP, XSHD, XRS,	Vон4	Feed current where IoH = −3.3mA	VDDd - 0.8			٧
Output voltage 4	PBLK, XCPOB	Vol4	Pull-in current where IoL = 2.4mA			0.4	٧
Output voltage 5	ID, EXP, HRO,	Voн5	Feed current where IoH = -2.4mA	VDDa - 0.8			٧
Output voltage 5	FRO	Vol5	Pull-in current where IoL = 4.8mA			0.4	٧
Output voltage 6	SUB	Vон ₆	Feed current where IoH = -4.0mA	VH - 0.25			٧
Output voltage 6	306	Vol6	Pull-in current where IoL = 5.4mA			VL + 0.25	٧
Output valtage 7	V4 V2	Vом7	Feed current where IoH = -5.0mA	VM - 0.25			٧
Output voltage 7	V1, V3	Vol7	Pull-in current where IoL = 10.0mA			VL + 0.25	V
		Vом101	Feed current where IoH = −7.2mA	VH - 0.25			V
Output valtage	\/2	Vом102	Pull-in current where IoL = 5.0mA			VM + 0.25	V
Output voltage 8	V2A, V2B	Vol8	Feed current where IoH = −5.0mA	VM - 0.25			V
		Vol8	Pull-in current where IoL = 10.0mA			VL + 0.25	٧

Inverter I/O Characteristics for Oscillation

(Within the recommended operating conditions)

Item	Pins	Symbol	Conditions	Min.	Тур.	Max.	Unit
Logical Vth	OSCI	LVth			VDDa/2		V
	OSCI	Vıн		0.7VDDa			V
Input voltage	USCI	VIL				0.3VDDa	V
	osco	Vон	Feed current where Ioн = -6.0mA	VDDa/2			V
Output voltage		Vol	Pull-in current where IoL = 6.0mA			VDDa/2	V
Feedback resistor	OSCI, OSCO	RFB	VIN = VDDa or Vss	500k	2M	5M	Ω
Oscillator frequency	OSCI, OSCO	f		20		50	MHz

Base Oscillation Clock Input Characteristics

(Within the recommended operating conditions)

Item	Pins	Symbol	Conditions	Min.	Тур.	Max.	Unit
Logical Vth		LVth			VDDa/2		V
land valtage	CKI	ViH		0.7VDDa			V
Input voltage	CKI	VIL				0.3VDDa	V
Input amplitude		Vin	fmax 50MHz sine wave	0.3			Vp-p

^{*1} Input voltage is the input voltage characteristics for direct input from an external source. Input amplitude is the input amplitude characteristics for input through capacitor.

Switching Characteristics

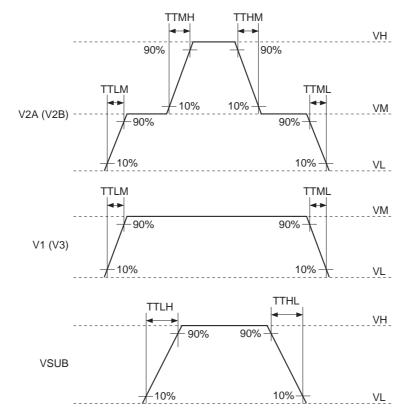
(VH = 15.0V, VM = GND, VL = -8.5V)

Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
	TTLM	VL to VM		350	550	ns
Rise time	TTMH	VM to VH		450	700	ns
	TTLH	VL to VH		50	80	ns
	TTML	VM to VL		250	400	ns
Fall time	TTHM	VH to VM		300	450	ns
	TTHL	VH to VL		50	80	ns
	VCLH				1.0	V
Output noise voltage	VCLL				1.0	٧
	VCMH				1.0	V
	VCML				1.0	V

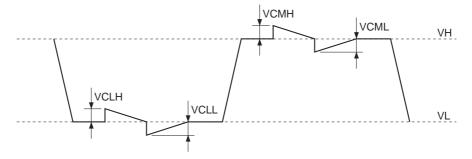
^{*1} The MOS structure of this IC has a low tolerance for static electricity, so full care should be given for measures to prevent electrostatic discharge.

^{*2} For noise and latch-up countermeasures, be sure to connect a bypass capacitor (0.1μF or more) between each power supply pin (VH, VL) and GND.

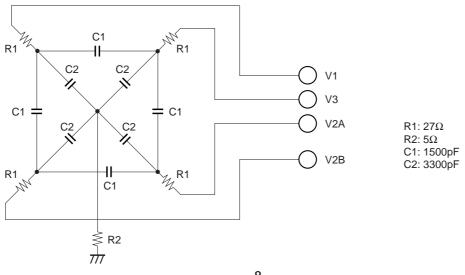
Switching Waveforms



Waveform Noise

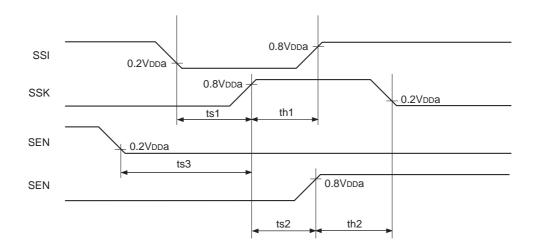


Measurement Circuit



AC Characteristics

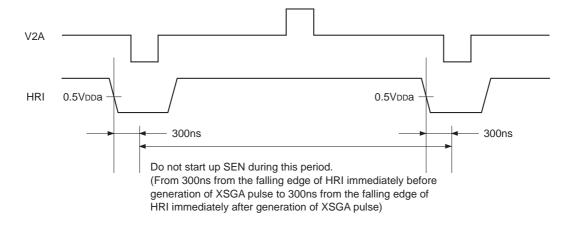
1) AC characteristics between the serial interface clocks



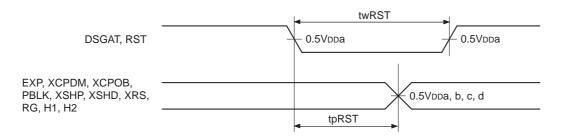
(Within the recommended operating conditions)

Symbol	Definition	Min.	Тур.	Max.	Unit
ts1	SSI setup time, activated by the rising edge of SSK	20			ns
th1	SSI hold time, activated by the rising edge of SSK	20			ns
ts2	SSK setup time, activated by the rising edge of SEN	20			ns
th2	SSK hold time, activated by the rising edge of SEN	20			ns
ts3	SEN setup time, activated by the rising edge of SSK	20			ns
fk	SSK frequency			7.15	MHz

2) Serial interface clock internal loading characteristics



3) Output timing characteristics using DSGAT and RST

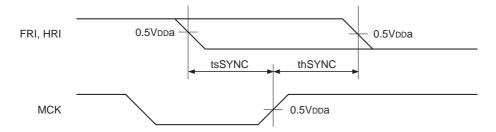


H1 and H2 load = 270pF

EXP, XCPDM, PBLK, XSHP, XSHD, XRS and RG load = 10pF (Within the recommended operating conditions)

Symbol	Definition	Min.	Тур.	Max.	Unit
tpRST	Time until the above outputs reach the specified value after the fall of DSGAT and RST			125	ns
twRST	RST and DSGAT pulse width	10			ns

4) FRI and HRI loading characteristics

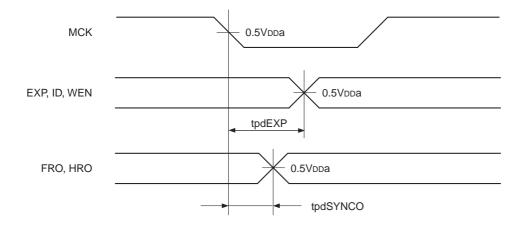


MCK load = 35pF

(Within the recommended operating conditions)

Symbol	Definition	Min.	Тур.	Max.	Unit
tsSYNC	FRI and HRI setup time, activated by the rising edge of MCK	5			ns
thSYNC	FRI and HRI hold time, activated by the rising edge of MCK	5			ns

5) Output variation characteristics of ID, WEN, EXP, FRO and HRO



EXP, ID and WEN load = 10pF

(Within the recommended operating conditions)

Symbol	Definition	Min.	Тур.	Max.	Unit
tpdEXP	Time until the WEN, ID and EXP outputs change after the fall of MCK	0.5		8.5	ns
tpdSYNCO	Time until the FRO and HRO outputs change after the fall of MCK	0.5		3.5	ns

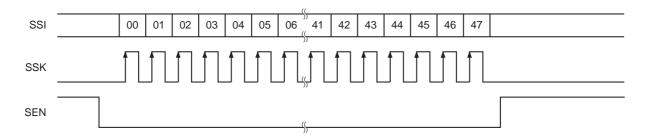
Description of Operation

1. Progressive Scan CCD drive pulse generation

- Combining this IC with a crystal oscillator generates a fundamental frequency of 28.636MHz.
- CCD drive pulse generation is synchronized with HRI and FRI.
- The CCD drive method can be changed to various modes by inputting serial data or parallel data to the CXD2460R.
- The various drive methods possessed by the CXD2460R are shown in the Timing Charts A-1 to 3 (V rate) and B-1 to 6 (H rate).

2. Serial data input method

• All CXD2460R operations can be controlled via the serial data. The serial data format is as follows.



Serial data format

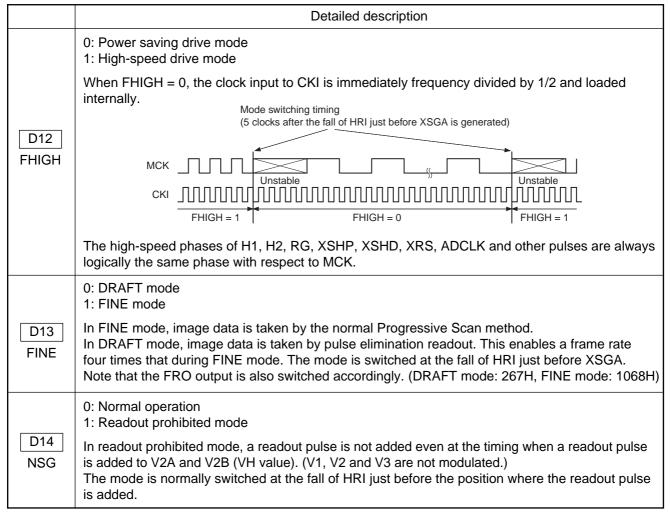
Serial data

Data	Symbol	Function		When reset
D00 to D07	CHIP	Chip switching	See D00 to D07 CHIP.	All 0
D08 to D11	CTGRY	Category switching	See D08 to D11 CTGRY.	All 0
D12 to D39	DATA	Control data for each category The meaning of this CTGRY control data differs according to the category set by D08 to D11.	See D12 to D39 DATA.	All 0
D40 to D47	Checksum bits	Checksum bits	See D40 to D47 CHKSUM.	All 0

3. Serial data and description of functions

		Detailed description												
D00 to	R when D00 and D07 are "1". However, this													
D07 D06 D05 D04 D03 D02 D01 D00 Function														
CHIP	1	0	0	0	0	0	0	1	Loading to the CXD2460R					
	This C	TGRY	data i	ndicate	s the	functio	ns tha	t the s	erial interface data controls.					
D 00	D11	D10	D09	D08		Function								
D08 to	0	0	0	0	Mod	e cont	rol dat	а						
D11	0	0	1	0	Elec	tronic	shutte	contr	ol data					
CTGRY	0	0	1	1	High	-speed	d phas	e adju	stment data (Set all of D12 to D39 to "0".)					
	0	1	0	0	Syst	System setting data								
	Input	nibited.												

CTGRY: Mode control data



Detailed description 0: Normal operation 1: FS mode In order to increase the frame rate, a certain portion of the captured image of CCD can be cut out by performing high-speed sweep. In FS mode, high-speed sweep is performed for the V registers of the entire image (period Z) after FRI input. Next, high-speed sweep is performed again for only the desired period (period X) after generating the XSGA/XSGB pulses. Then, after performing normal V transfer and outputting the effective signal (period Y), high-speed sweep is performed for the entire image again by inputting FRI at the desired timing. This makes it possible to take only the desired portion in the V direction, thus effectively increasing the frame rate. Operation is fixed during period Z, with 20 lines swept every 1H and repeating over a 69H period. During period X, first XSGA/XSGB are generated. These pulses are dependent on serial data FINE. In other words, if FINE = 1, then both XSGA and XSGB are generated, while if FINE = 0, only XSGA is generated. Next, sweep operation starts. This period is set in serial data FVFS (system setting data: D21 to D26) in HRI units. If FINE = 1, sweeping is performed at 8 lines per 1H, and if FINE = 0, sweeping is performed at 20 lines per 1H. The operations of V1, V2 and V3 after readout during period Y differ depending on the FINE D15 data. FS • When the frame rate is increased as the vertical effective signal Y line (example) Χ Sweep variable period (period X) 1068 Effective signal period (period Y) Sweep fixed period (period Z) Ζ Reset by FRI after Timing chart normal transfer FRI Χ 69H Set by FVFS (Fix) D16 Set to "0". to D17

to
D18
STB

Detailed description

Operation control settings

The operating mode control bits are loaded to the CXD2460R at the rise timing of the SEN input, and control is applied immediately.

D19	D18	Symbol	Control mode
0	0	CAM	Normal operation mode
0	1	SLP	Sleep mode (mode for the status where CCD drive is not required)
1	Х	STN	Standby mode

Pin status during operation control

		<u> </u>									
Pin No.	Symbol	CAM	SLP	STN	RST*	Pin No.	Symbol	CAM	SLP	STN	RST*
1	СКО	ACT	ACT	ACT	ACT	25	MCK	ACT	ACT	ACT	ACT
2	Vss0	_	_	_	_	26	VDD1		_	_	_
3	CKI	ACT	ACT	ACT	ACT	27	2MCK	ACT	ACT	ACT	ACT
4	osco	ACT	ACT	ACT	ACT	28	TEST2				_
5	OSCI	ACT	ACT	ACT	ACT	29	SEN	ACT	ACT		_
6	VDD0		_	_	_	30	SSK	ACT	ACT		_
7	TEST1	_	_	_	_	31	SSI	ACT	ACT		_
8	AVD0	_	_	_	_	32	ID	ACT	L	L	L
9	RG	ACT	L	L	L	33	EXP	ACT	L	L	L
10	Vss1	_	_	_	_	34	HRO	ACT	ACT	L	L
11	Vss2	_	_	_	_	35	FRO	ACT	ACT	L	L
12	H1	ACT	L	L	L	36	Vss4		_		_
13	H2	ACT	L	L	L	37	HRI	ACT	ACT		_
14	AVD1		_	_	_	38	FRI	ACT	ACT		_
15	XCPDM	ACT	L	L	L	39	VM		_		_
16	AVD2	_	_	_	_	40	V1	ACT	VM	VM	VM
17	XSHP	ACT	L	L	L	41	V3	ACT	VM	VM	VM
18	XSHD	ACT	L	L	L	42	V2A	ACT	VH	VH	VH
19	XRS	ACT	L	L	L	43	VH		_		_
20	Vss3		_	_	_	44	V2B	ACT	VH	VH	VH
21	PBLK	ACT	L	L	L	45	SUB	ACT	VH	VH	VH
22	ХСРОВ	ACT	L	L	L	46	VL		_		
23	ADCLK	ACT	L	L	L	47	DSGAT	ACT	ACT	L	L
24	RST	ACT	ACT	ACT	ACT	48	PS	ACT	ACT	ACT	ACT

^{*} See "6. RST pulse" for a detailed description of RST.

Note) ACT indicates circuit operation, and L indicates "low" output level in the controlled status. For sleep mode or standby mode, stop supplying VH and VL power supplies with CCD image sensor.

	Detailed description
D20 EXPXEN	O: The EXP pulse indicating the exposure period is generated (when PS = low). 1: The EXP pulse indicating the exposure period is not generated (when PS = low), and is constantly fixed to low. This bit is invalid when STATUS = 1. Note that the STB setting has priority.
to D24	Invalid data
D25 to D29	Low-speed electronic shutter setting. The value set here is the number of FR during which readout operation is not performed even if there is input. The setting range is from "0" to "31". When set to "0", readout operation is performed at the first FR. When FS = 1, this bit is invalid.
VSHUT	MSB LSB Function
	D29 D28 D27 D26 D25 Number of FR during which readout operation is not performed
D30 to D39	Invalid data

CXD2460R clock system

When using a 28.636MHz crystal

	FHIGH	FINE	MCK frequency	2MCK pin output	Frame rate	
Mode1	1	1	14.3MHz	28.6MHz	7.5Frame/s	Basic
Mode2	1	0	14.3MHz	28.6MHz	30Frame/s	DRAFT
Mode3	0	0	7.2MHz	14.3MHz	15Frame/s	Power-save

Note) Combinations of FHIGH and FINE other than those listed above are prohibited.

CTGRY: Electronic shutter control data

	Detailed description												
D12 to	High-speed electronic shutter setting. The value set here is the number of SUB pulses from FR to the r	ext FR.											
D22	MSB LSB Function												
HSHUT	D22 D21 D20 D19 D18 D17 D16 D15 D14 D13 D12	Number of SUB pulses setting											
D23 to D39	Input "0".												

High-speed and low-speed electronic shutter can be used together. Therefore, the exposure time is as follows:

FR cycle \times VSHUT + (fv – HSHUT) \times HR cycle + 634/MCK frequency [Hz] = Exposure time [s] (fv: Number of HR in 1FR)

CTGRY: System setting data

	Detailed description											
D12 SGXEN	O: Internal SSG (Sync Signal Generator) functions operate to generate FRO and HRO. 1: Internal SSG functions are stopped, and the FRO and HRO pulses are fixed to low. Note that the STB setting has priority. Set SGXEN to "1" in the case of input of a CXD2460R sync signal from the outside.											
D13 EXSG		0: Normal operation 1: XSGA and XSGB are output from the HRO and FRO pins. Note that the output pulse amplitude is Vss to VDDa.										
	These bits select the pul	se out	put from the ID pin.									
			D	15]							
D14			0	1								
to D15	D14	0	ID pulse output	WEN pulse output								
IDSEL	D14	1	XSUB pulse output	ID pulse output								
	XSUE	: Inve	rted SUB pulse outp	ut at the amplitude of	Vss to VDDa							
D16 VTXEN D17 CHKSUM	O: VT (readout clock) is a 1: VT is not added to V2 During readout, only the Note that this setting has O: Checksum is not performent 1: Checksum is performent O: The EXP pulse is outp	modu priori ormed gister ed. Th	and V3. lation necessary for lifty over mode control and the checksum d .) is data is reflected ev	readout is performed data NSG (D14). ata is invalid. (Howe	ver, dummy data must be							
D18 STATUS		check e rise	ssum results from the of SEN, and reset hi	·	l low if the results are NG. SEN. This pulse has							
to D22	Input "0".											
	These bits set the high-s	peed	sweep period (unit: H	I) in FS mode.								
D23	MSB		LSB									
D29	D29 D28 D27 D26	D25	5 D24 D23									
FVFS	The high-speed sweep is 1H when FINE = 0.	perfo	omed for 8 lines for e	very 1H when FINE =	= 1, and 20 lines for every							

	Detailed description
D30 XVCK	0: Normal operation 1: V1, V2 and V3 are inverted and output as XV1, XV2 and XV3. The amplitude is from VL to VM.
D31 to D39	Invalid data

CHKSUM

						ĺ	Detaile	d desc	ription	
	These a	are the	check	ksum b	its.					
D40 to D47	+) [MSB D07 D15 D23 D31 D39	D06 D14 D22 D30 D38	D05 D13 D21 D29 D37 D45	D04 D12 D20 D28 D36	D03 D11 D19 D27 D35 D43	D02 D10 D18 D26 D34 D42		LSB D00 D08 D16 D24 D32 D40	→ CHKSUM e checksum results are OK.
	Data is	not ret hen Cl	flected	to the	regist	ers if c	hecksu	um is N	۱G.	oksum is OK. OK and the data is reflected to the

4. Shutter speed setting specifications when PS = H

When PS = H, the CXD2460R can be controlled without inputting serial data by using the SEN, SSK and SSI pins.

Pin			Wh	en L			When H		
SEN	FHIGH (horizontal drive frequency)	Serial regi	Serial register FHIGH = 0. Serial register FHIGH = 1.						
SSK	FINE (readout method)		Serial register FINE = 0 and the CXD2460R operates in DRAFT mode. Serial register FINE = 1 and the CXD2460R operates in FINE mo						
SSI	HSHUT, VSHUT (exposure time)		SEN	L H		SSI	H 1052 1002 1034 935 er: When SSI = H (1/2 er: When SSI = L (1/60	, i	

Other registers hold the value input when PS = L, and assume the status indicated by STB when the RST pulse is input.

5. Reflection position of each data

Each serial data is reflected at the timing shown in the table below. The reflection position is the same when PS = H. When using the low-speed electronic shutter, the data is not reflected at FR where XSG is not generated (a readout pulse is not added to V2A).

Table 5-1. Serial data reflection timing

Data	Reflection position
Mode control data (STB)	SEN rise
Mode control data (EXPXEN)	XSGA pulse rise
Mode control data (other than STB and EXPXEN)	HRI*1 fall just before XSGA pulse generation
Electronic shutter control data	HRI*2 fall just after XSGA pulse generation
High-speed phase adjustment data	HRI*1 fall just before XSGA pulse generation
System setting data (SGXEN)	SEN rise
System setting data (other than SGXEN)	HRI*2 fall just before XSGA pulse generation

^{*1} For FS mode, 7HRI later from FRI fall.

6. RST pulse

Setting Pin 30 to low resets the system. The serial data values after reset are as shown in the "Serial data" table.

Also, some internal circuits stop operating when RST = L. For a description of the pin status when RST = L, see the "Pin status during operation control" table given in the detailed description of STB under "3. Serial data and description of functions".

7. DSGAT

DSGAT is ON when low and the CXD2460R is set to sleep mode as with SLP of STB.

Note that control is applied when either or both of DSGAT and SLP are ON. Also, when STN is ON, the CXD2460R is set to standby mode regardless of the DSGAT status.

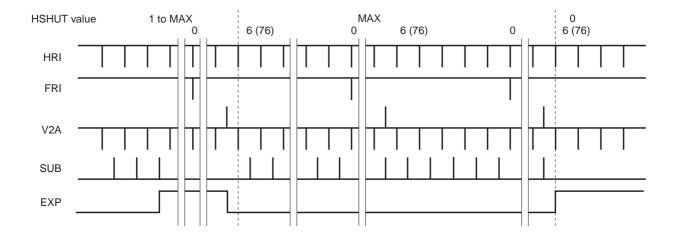
8. EXP pulse

The EXP pulse indicates the exposure period.

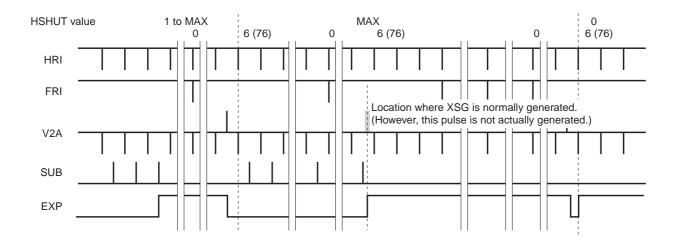
The details are shown on the following pages.

^{*2} For FS mode, 8HRI later from FRI fall.

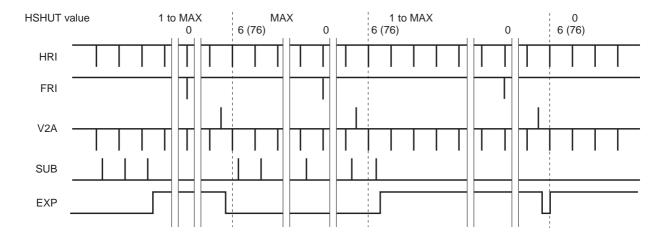
(1) HSHUT ≥ MAX



(2) HSHUT ≥ MAX (with low-speed electronic shutter)

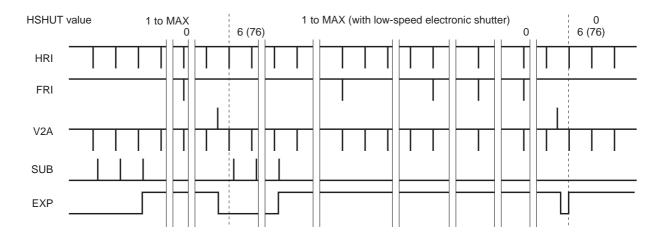


(3) $1 \le HSHUT < MAX$

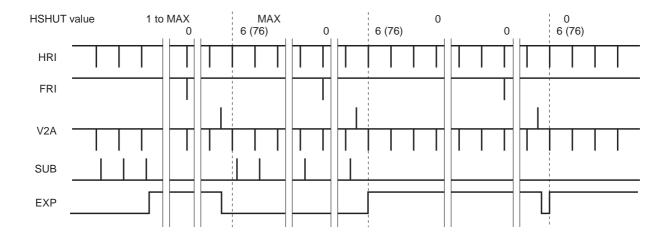


Numbers in parentheses are for FS mode.

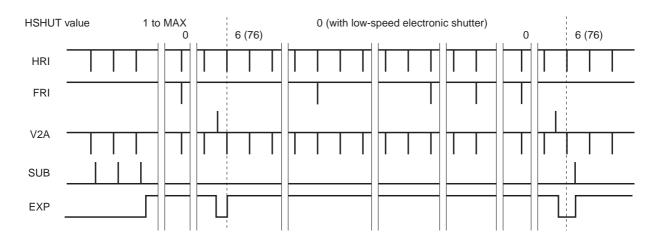
(4) 1 ≤ HSHUT < MAX (with low-speed electronic shutter)



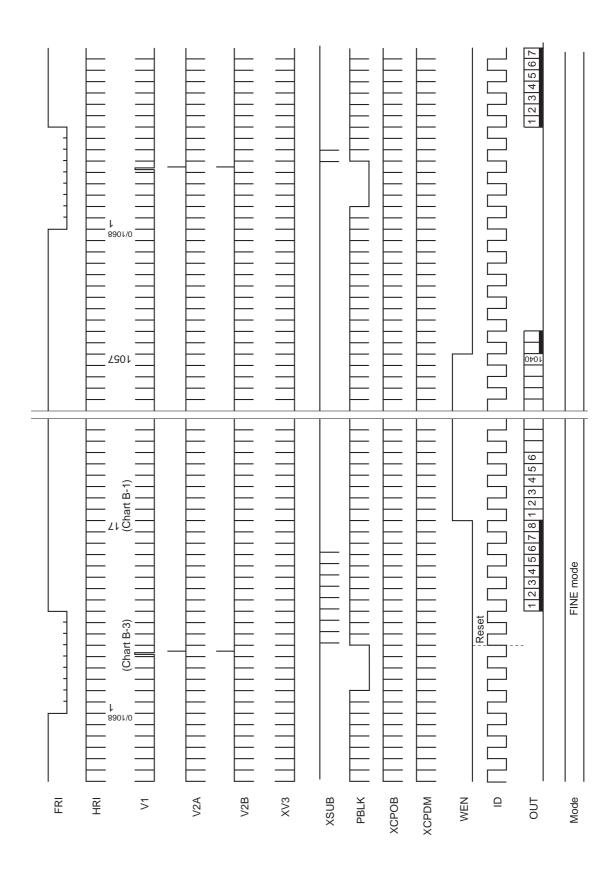
(5) HSHUT = 0



(6) HSHUT = 0 (with low-speed electronic shutter)



Numbers in parentheses are for FS mode.



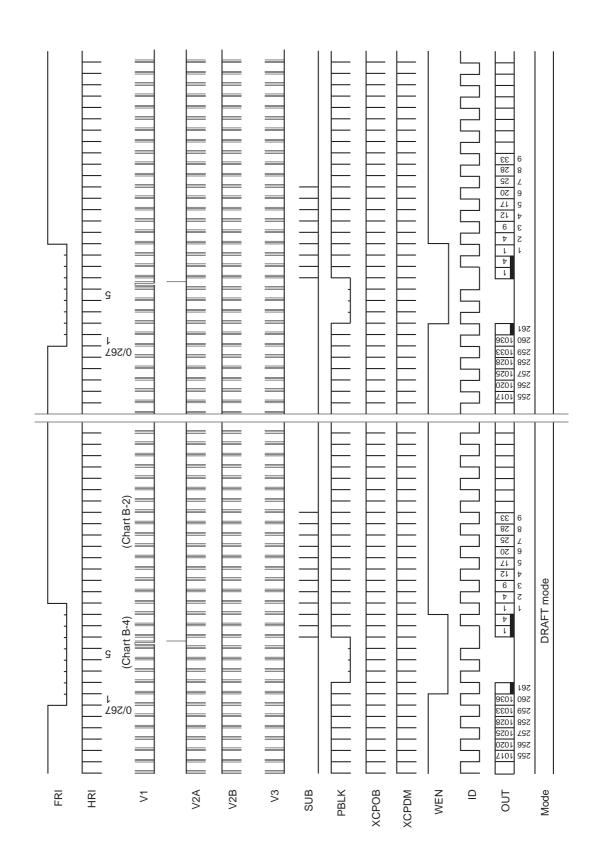
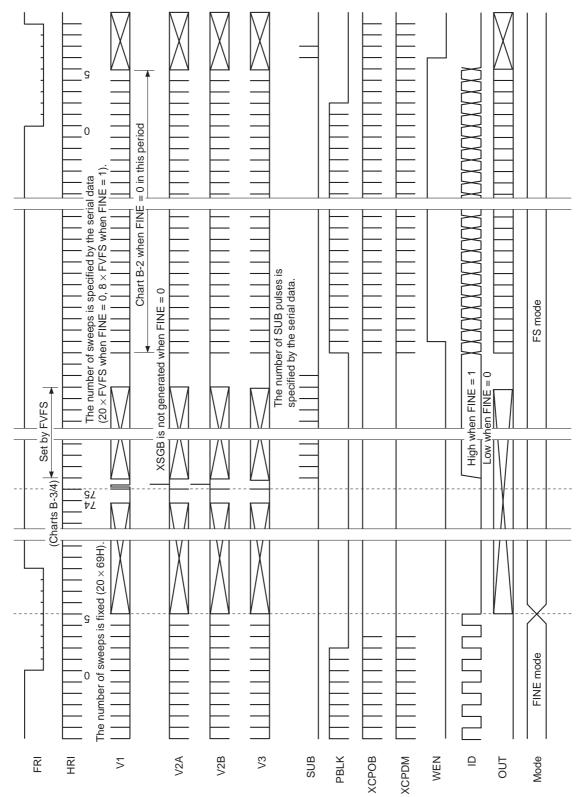
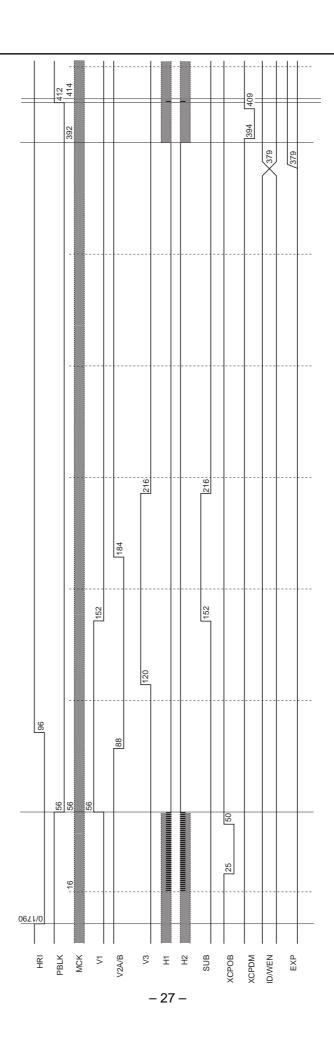
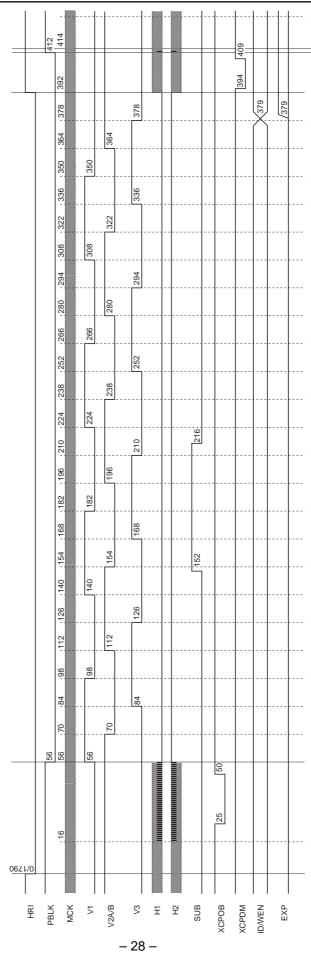


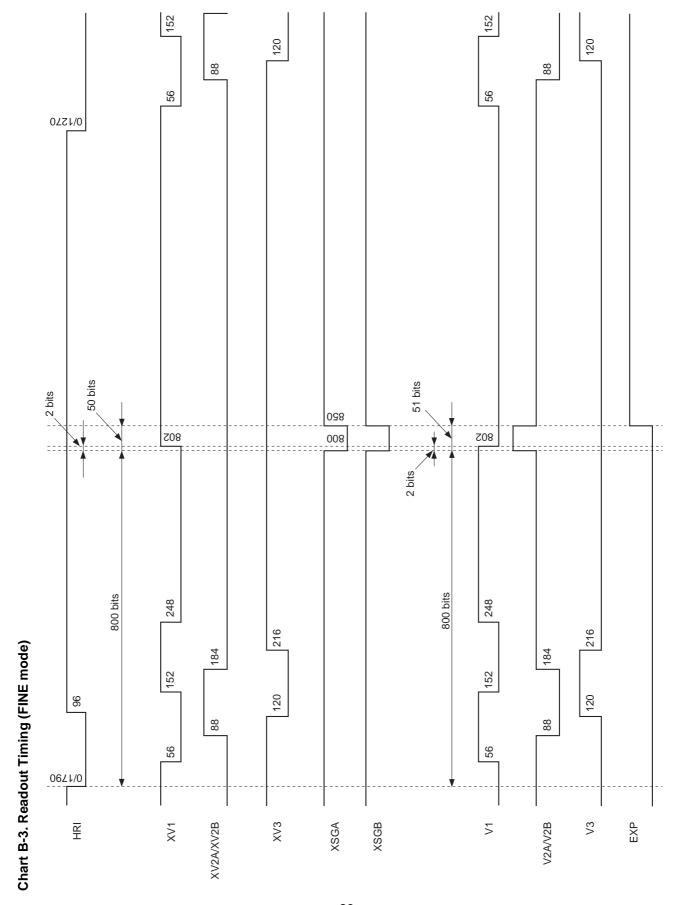
Chart A-3. FS Mode (Vertical synchronization)



The mode is switched at the point where XSG is normally generated.







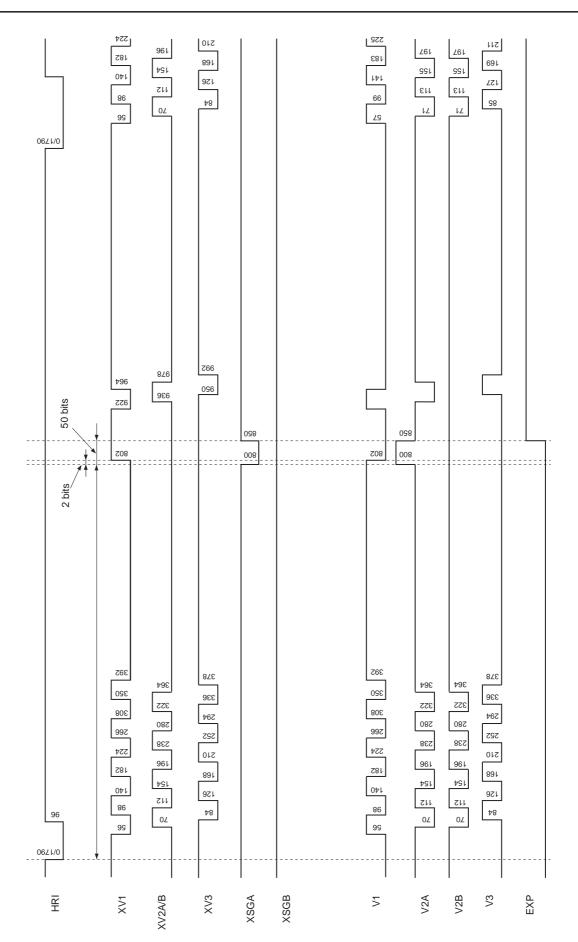
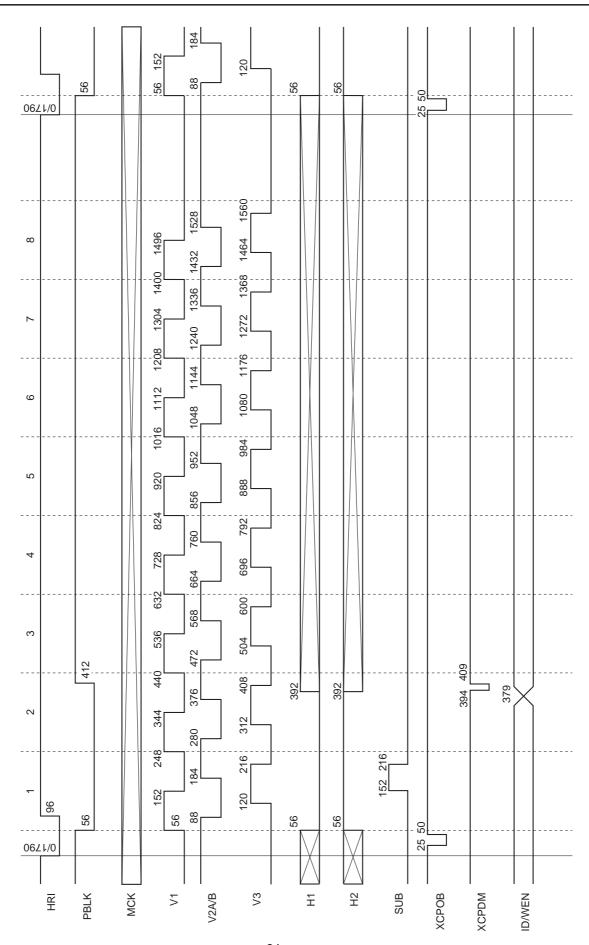
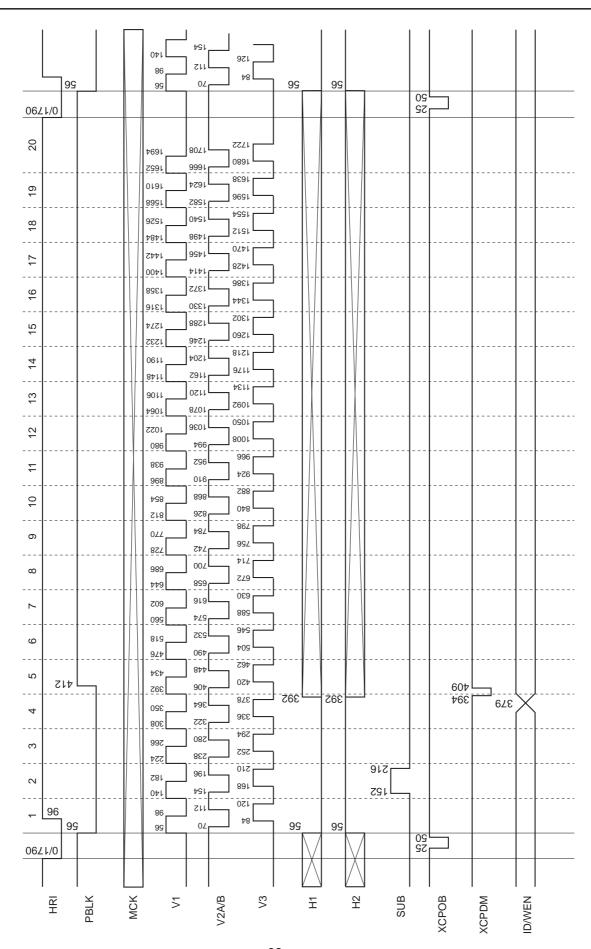
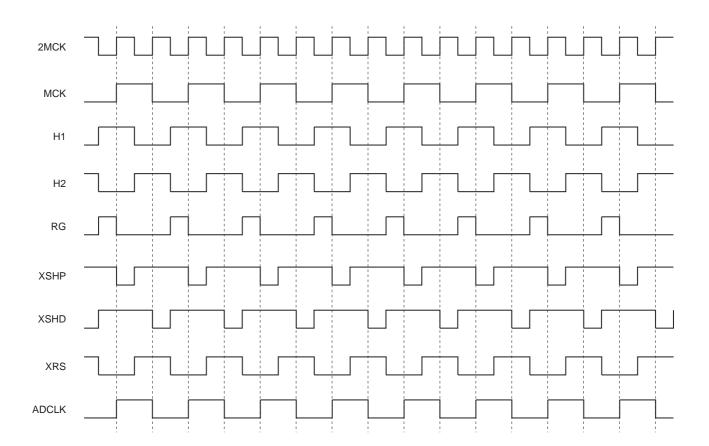


Chart B-5. FS Mode: V clock continuous drive (FINE = 1)

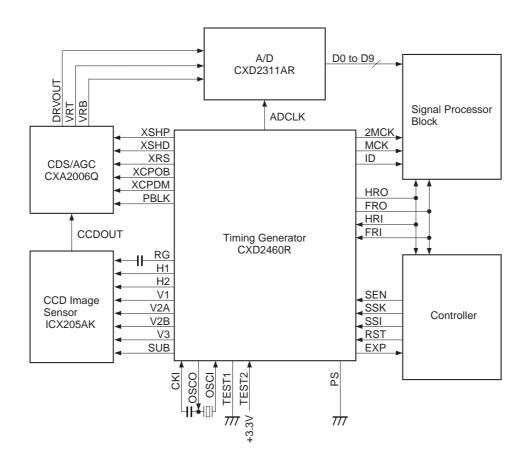




Logical Phase



Application Circuit

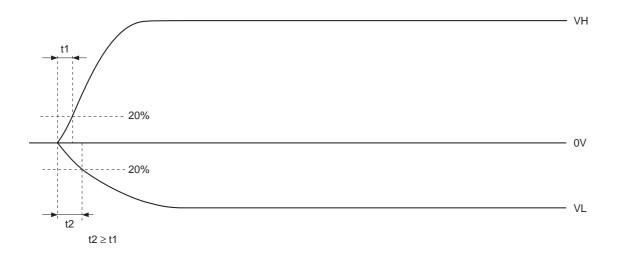


For making FR and HR outside the CXD2460R, configure a circuit that counts MCK. (Using 2MCK, CKO, etc. is not recommended.) Also, set system setting data, SGXEN (D12) to "1" and stop a built-in SSG. Use crystal oscillator (fundamental wave) as base oscillation. Be sure to input duty 50% pulse when crystal oscillator is used.

Application circuits shown are typical examples illustrating the operation of the devices. Sony cannot assume responsibility for any problems arising out of the use of these circuits or for any infringement of third party patent and other right due to same.

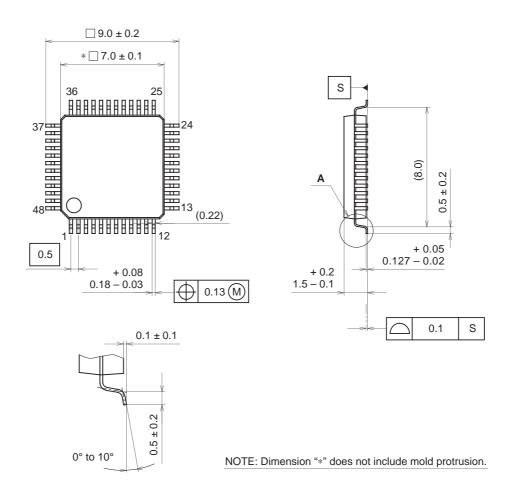
Notes on Turning Power ON

To avoid setting VSUB pin of the CCD image sensor negative potential, the former two power supplies should be raised by the following order among three power supplies, VL and VH.



Package Outline Unit: mm

48PIN LQFP (PLASTIC)



DETAIL A

SONY CODE	LQFP-48P-L01
EIAJ CODE	LQFP048-P-0707
JEDEC CODE	

PACKAGE STRUCTURE

PACKAGE MATERIAL	EPOXY RESIN
LEAD TREATMENT	SOLDER/PALLADIUM PLATING
LEAD MATERIAL	42/COPPER ALLOY
PACKAGE MASS	0.2g